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Dimensions	
D	26.9mm MAX
L	6.35mm MIN
H	2.54mm +/-0.127mm
F	1.397mm +/-0.25mm
A	6.6mm MAX
B	8.64mm MAX
C	6.35mm +/-0.635mm
E	7.62mm MAX
K	0.5mm +/-0.05mm

Packaging Specifications	
Packaging	Waffle, Box
Packaging Quantity	25

General Information	
Series	KPS-MCL Indust COG HT200C
Style	Leaded Stacked Chip
Description	Low Loss, Low ESR, Stacked Ceramic Chips
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance
RoHS	Yes
SCIP Number	297427bb-2a48-4853-b594-641304a2cc24
Termination	Silver
Lead	Straight Leads
AEC-Q200	No
Notes	Number of chips in this stack: 10.

Specifications	
Capacitance	1.2 uF
Capacitance Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	830 MOhms

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